

Embedded Die Packaging Technology Market by Platform (Embedded Die in IC Package Substrate, Embedded Die in Rigid Board, Embedded Die in Flexible Board), Industry Vertical (Consumer Electronics, IT and Telecommunication, Automotive, Healthcare, and Others), and Region 2024-2032

<https://marketpublishers.com/r/EB82EBA3BFAAEN.html>

Date: April 2024

Pages: 138

Price: US\$ 3,899.00 (Single User License)

ID: EB82EBA3BFAAEN

Abstracts

The global embedded die packaging technology market size reached US\$ 92.3 Million in 2023. Looking forward, IMARC Group expects the market to reach US\$ 246.1 Million by 2032, exhibiting a growth rate (CAGR) of 11.17% during 2024-2032.

Embedded die packaging technology is used to embed components inside the substrate via a multi-step manufacturing process. It comprises flip-chip chip scale packaging (FC CSP) and wafer-level chip scale packaging (WL CSP) to improve the efficiency of the system. It creates more space for other components by shrinking overall solutions in the printed circuit board (PCB). It also provides surface-mount technology (SMT) integration and a flexible routing solution to reduce printed circuit board (PCB) size. It offers design flexibility that shifts from 2D to 3D while reducing distortion and power loss. As a result, embedded die packaging technology finds extensive application in electronics, information and technology (IT), automotive, healthcare, and telecommunication industries across the globe.

Embedded Die Packaging Technology Market Trends:

At present, there is an increase in the miniaturization of electronic circuits in microelectronic devices around the world. This, along with the burgeoning semiconductor industry, represents one of the key factors driving the market. Moreover, embedded die packaging technology offers several benefits, such as upgraded

electrical and thermal performance, heterogeneous integration, and streamlined logistics for original equipment manufacturers (OEMs), which are contributing to the growth of the market. In addition, the increasing adoption of autonomous robots for professional services in various industries is offering lucrative growth opportunities to industry investors. Besides this, the growing utilization of embedded die packaging technology in smartphones and wearable devices to enhance the available space and integrate more components is positively influencing the market. Additionally, there is a rise in the demand for embedded die packaging technology with integrated internet of things (IoT) across the globe. This, coupled with the increasing sales of portable electronic devices, such as laptops, computers, tablets, e-readers, smartphones, MP3 players, drones, and electronic toys, is bolstering the growth of the market.

Key Market Segmentation:

IMARC Group provides an analysis of the key trends in each sub-segment of the global embedded die packaging technology market report, along with forecasts at the global, regional and country level from 2024-2032. Our report has categorized the market based on platform and industry vertical.

Breakup by Platform:

Embedded Die in IC Package Substrate

Embedded Die in Rigid Board

Embedded Die in Flexible Board

Breakup by Industry Vertical:

Consumer Electronics

IT and Telecommunication

Automotive

Healthcare

Others

Breakup by Region:

North America

United States

Canada

Asia-Pacific

China

Japan
India
South Korea
Australia
Indonesia
Others
Europe
Germany
France
United Kingdom
Italy
Spain
Russia
Others
Latin America
Brazil
Mexico
Others
Middle East and Africa

Competitive Landscape:

The competitive landscape of the industry has also been examined along with the profiles of the key players being Amkor Technology Inc., ASE Technology Holding Co. Ltd., AT & S Austria Technologie & Systemtechnik Aktiengesellschaft, Fujikura Ltd., Infineon Technologies AG, Microsemi Corporation (Microchip Technology Inc.), Schweizer Electronic AG and TDK Electronics AG (TDK Corporation). Kindly, note that this only represents a partial list of companies, and the complete list has been provided in the report.

Key Questions Answered in This Report

1. What was the size of the global embedded die packaging technology market in 2023?
2. What is the expected growth rate of the global embedded die packaging technology market during 2024-2032?
3. What are the key factors driving the global embedded die packaging technology market?
4. What has been the impact of COVID-19 on the global embedded die packaging technology market?
5. What is the breakup of the global embedded die packaging technology market based

on the platform?

6. What is the breakup of the global embedded die packaging technology market based on the industry vertical?

7. What are the key regions in the global embedded die packaging technology market?

8. Who are the key players/companies in the global embedded die packaging technology market?

Contents

1 PREFACE

2 SCOPE AND METHODOLOGY

- 2.1 Objectives of the Study
- 2.2 Stakeholders
- 2.3 Data Sources
 - 2.3.1 Primary Sources
 - 2.3.2 Secondary Sources
- 2.4 Market Estimation
 - 2.4.1 Bottom-Up Approach
 - 2.4.2 Top-Down Approach
- 2.5 Forecasting Methodology

3 EXECUTIVE SUMMARY

4 INTRODUCTION

- 4.1 Overview
- 4.2 Key Industry Trends

5 GLOBAL EMBEDDED DIE PACKAGING TECHNOLOGY MARKET

- 5.1 Market Overview
- 5.2 Market Performance
- 5.3 Impact of COVID-19
- 5.4 Market Forecast

6 MARKET BREAKUP BY PLATFORM

- 6.1 Embedded Die in IC Package Substrate
 - 6.1.1 Market Trends
 - 6.1.2 Market Forecast
- 6.2 Embedded Die in Rigid Board
 - 6.2.1 Market Trends
 - 6.2.2 Market Forecast
- 6.3 Embedded Die in Flexible Board

- 6.3.1 Market Trends
- 6.3.2 Market Forecast

7 MARKET BREAKUP BY INDUSTRY VERTICAL

- 7.1 Consumer Electronics
 - 7.1.1 Market Trends
 - 7.1.2 Market Forecast
- 7.2 IT and Telecommunication
 - 7.2.1 Market Trends
 - 7.2.2 Market Forecast
- 7.3 Automotive
 - 7.3.1 Market Trends
 - 7.3.2 Market Forecast
- 7.4 Healthcare
 - 7.4.1 Market Trends
 - 7.4.2 Market Forecast
- 7.5 Others
 - 7.5.1 Market Trends
 - 7.5.2 Market Forecast

8 MARKET BREAKUP BY REGION

- 8.1 North America
 - 8.1.1 United States
 - 8.1.1.1 Market Trends
 - 8.1.1.2 Market Forecast
 - 8.1.2 Canada
 - 8.1.2.1 Market Trends
 - 8.1.2.2 Market Forecast
- 8.2 Asia-Pacific
 - 8.2.1 China
 - 8.2.1.1 Market Trends
 - 8.2.1.2 Market Forecast
 - 8.2.2 Japan
 - 8.2.2.1 Market Trends
 - 8.2.2.2 Market Forecast
 - 8.2.3 India
 - 8.2.3.1 Market Trends

- 8.2.3.2 Market Forecast
- 8.2.4 South Korea
 - 8.2.4.1 Market Trends
 - 8.2.4.2 Market Forecast
- 8.2.5 Australia
 - 8.2.5.1 Market Trends
 - 8.2.5.2 Market Forecast
- 8.2.6 Indonesia
 - 8.2.6.1 Market Trends
 - 8.2.6.2 Market Forecast
- 8.2.7 Others
 - 8.2.7.1 Market Trends
 - 8.2.7.2 Market Forecast
- 8.3 Europe
 - 8.3.1 Germany
 - 8.3.1.1 Market Trends
 - 8.3.1.2 Market Forecast
 - 8.3.2 France
 - 8.3.2.1 Market Trends
 - 8.3.2.2 Market Forecast
 - 8.3.3 United Kingdom
 - 8.3.3.1 Market Trends
 - 8.3.3.2 Market Forecast
 - 8.3.4 Italy
 - 8.3.4.1 Market Trends
 - 8.3.4.2 Market Forecast
 - 8.3.5 Spain
 - 8.3.5.1 Market Trends
 - 8.3.5.2 Market Forecast
 - 8.3.6 Russia
 - 8.3.6.1 Market Trends
 - 8.3.6.2 Market Forecast
 - 8.3.7 Others
 - 8.3.7.1 Market Trends
 - 8.3.7.2 Market Forecast
- 8.4 Latin America
 - 8.4.1 Brazil
 - 8.4.1.1 Market Trends
 - 8.4.1.2 Market Forecast

8.4.2 Mexico

8.4.2.1 Market Trends

8.4.2.2 Market Forecast

8.4.3 Others

8.4.3.1 Market Trends

8.4.3.2 Market Forecast

8.5 Middle East and Africa

8.5.1 Market Trends

8.5.2 Market Breakup by Country

8.5.3 Market Forecast

9 SWOT ANALYSIS

9.1 Overview

9.2 Strengths

9.3 Weaknesses

9.4 Opportunities

9.5 Threats

10 VALUE CHAIN ANALYSIS

11 PORTERS FIVE FORCES ANALYSIS

11.1 Overview

11.2 Bargaining Power of Buyers

11.3 Bargaining Power of Suppliers

11.4 Degree of Competition

11.5 Threat of New Entrants

11.6 Threat of Substitutes

12 PRICE ANALYSIS

13 COMPETITIVE LANDSCAPE

13.1 Market Structure

13.2 Key Players

13.3 Profiles of Key Players

13.3.1 Amkor Technology Inc.

13.3.1.1 Company Overview

- 13.3.1.2 Product Portfolio
- 13.3.1.3 Financials
- 13.3.1.4 SWOT Analysis
- 13.3.2 ASE Technology Holding Co. Ltd.
 - 13.3.2.1 Company Overview
 - 13.3.2.2 Product Portfolio
 - 13.3.2.3 Financials
- 13.3.3 AT & S Austria Technologie & Systemtechnik Aktiengesellschaft
 - 13.3.3.1 Company Overview
 - 13.3.3.2 Product Portfolio
 - 13.3.3.3 Financials
- 13.3.4 Fujikura Ltd.
 - 13.3.4.1 Company Overview
 - 13.3.4.2 Product Portfolio
 - 13.3.4.3 Financials
 - 13.3.4.4 SWOT Analysis
- 13.3.5 Infineon Technologies AG
 - 13.3.5.1 Company Overview
 - 13.3.5.2 Product Portfolio
 - 13.3.5.3 Financials
 - 13.3.5.4 SWOT Analysis
- 13.3.6 Microsemi Corporation (Microchip Technology Inc.)
 - 13.3.6.1 Company Overview
 - 13.3.6.2 Product Portfolio
 - 13.3.6.3 SWOT Analysis
- 13.3.7 Schweizer Electronic AG
 - 13.3.7.1 Company Overview
 - 13.3.7.2 Product Portfolio
 - 13.3.7.3 Financials
- 13.3.8 TDK Electronics AG (TDK Corporation)
 - 13.3.8.1 Company Overview
 - 13.3.8.2 Product Portfolio

Kindly, note that this only represents a partial list of companies, and the complete list has been provided in the report

List Of Tables

LIST OF TABLES

Table 1: Global: Embedded Die Packaging Technology Market: Key Industry Highlights, 2023 and 2032

Table 2: Global: Embedded Die Packaging Technology Market Forecast: Breakup by Platform (in Million US\$), 2024-2032

Table 3: Global: Embedded Die Packaging Technology Market Forecast: Breakup by Industry Vertical (in Million US\$), 2024-2032

Table 4: Global: Embedded Die Packaging Technology Market Forecast: Breakup by Region (in Million US\$), 2024-2032

Table 5: Global: Embedded Die Packaging Technology Market: Competitive Structure

Table 6: Global: Embedded Die Packaging Technology Market: Key Players

List Of Figures

LIST OF FIGURES

Figure 1: Global: Embedded Die Packaging Technology Market: Major Drivers and Challenges

Figure 2: Global: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018-2023

Figure 3: Global: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 4: Global: Embedded Die Packaging Technology Market: Breakup by Platform (in %), 2023

Figure 5: Global: Embedded Die Packaging Technology Market: Breakup by Industry Vertical (in %), 2023

Figure 6: Global: Embedded Die Packaging Technology Market: Breakup by Region (in %), 2023

Figure 7: Global: Embedded Die Packaging Technology (Embedded Die in IC Package Substrate) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 8: Global: Embedded Die Packaging Technology (Embedded Die in IC Package Substrate) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 9: Global: Embedded Die Packaging Technology (Embedded Die in Rigid Board) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 10: Global: Embedded Die Packaging Technology (Embedded Die in Rigid Board) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 11: Global: Embedded Die Packaging Technology (Embedded Die in Flexible Board) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 12: Global: Embedded Die Packaging Technology (Embedded Die in Flexible Board) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 13: Global: Embedded Die Packaging Technology (Consumer Electronics) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 14: Global: Embedded Die Packaging Technology (Consumer Electronics) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 15: Global: Embedded Die Packaging Technology (IT and Telecommunication) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 16: Global: Embedded Die Packaging Technology (IT and Telecommunication) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 17: Global: Embedded Die Packaging Technology (Automotive) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 18: Global: Embedded Die Packaging Technology (Automotive) Market Forecast:

Sales Value (in Million US\$), 2024-2032

Figure 19: Global: Embedded Die Packaging Technology (Healthcare) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 20: Global: Embedded Die Packaging Technology (Healthcare) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 21: Global: Embedded Die Packaging Technology (Other Industry Verticals) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 22: Global: Embedded Die Packaging Technology (Other Industry Verticals) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 23: North America: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 24: North America: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 25: United States: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 26: United States: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 27: Canada: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 28: Canada: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 29: Asia-Pacific: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 30: Asia-Pacific: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 31: China: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 32: China: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 33: Japan: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 34: Japan: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 35: India: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 36: India: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 37: South Korea: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 38: South Korea: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 39: Australia: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 40: Australia: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 41: Indonesia: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 42: Indonesia: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 43: Others: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 44: Others: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 45: Europe: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 46: Europe: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 47: Germany: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 48: Germany: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 49: France: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 50: France: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 51: United Kingdom: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 52: United Kingdom: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 53: Italy: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 54: Italy: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 55: Spain: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 56: Spain: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 57: Russia: Embedded Die Packaging Technology Market: Sales Value (in

Million US\$), 2018 & 2023

Figure 58: Russia: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 59: Others: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 60: Others: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 61: Latin America: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 62: Latin America: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 63: Brazil: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 64: Brazil: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 65: Mexico: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 66: Mexico: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 67: Others: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 68: Others: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 69: Middle East and Africa: Embedded Die Packaging Technology Market: Sales Value (in Million US\$), 2018 & 2023

Figure 70: Middle East and Africa: Embedded Die Packaging Technology Market: Breakup by Country (in %), 2023

Figure 71: Middle East and Africa: Embedded Die Packaging Technology Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 72: Global: Embedded Die Packaging Technology Industry: SWOT Analysis

Figure 73: Global: Embedded Die Packaging Technology Industry: Value Chain Analysis

Figure 74: Global: Embedded Die Packaging Technology Industry: Porter's Five Forces Analysis

I would like to order

Product name: Embedded Die Packaging Technology Market by Platform (Embedded Die in IC Package Substrate, Embedded Die in Rigid Board, Embedded Die in Flexible Board), Industry Vertical (Consumer Electronics, IT and Telecommunication, Automotive, Healthcare, and Others), and Region 2024-2032

Product link: <https://marketpublishers.com/r/EB82EBA3BFAAEN.html>

Price: US\$ 3,899.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/EB82EBA3BFAAEN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below
and fax the completed form to +44 20 7900 3970